

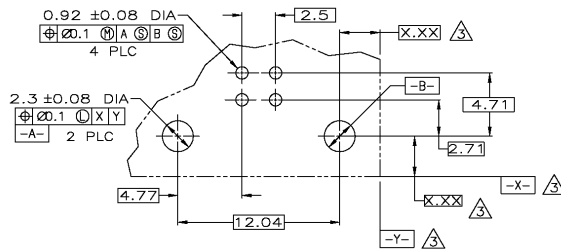
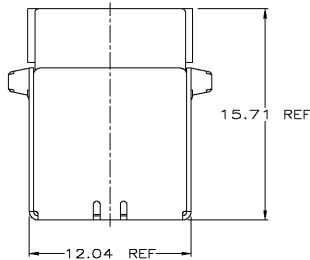
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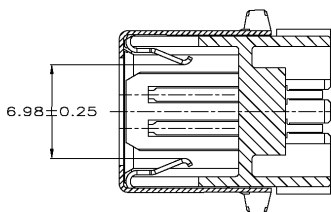
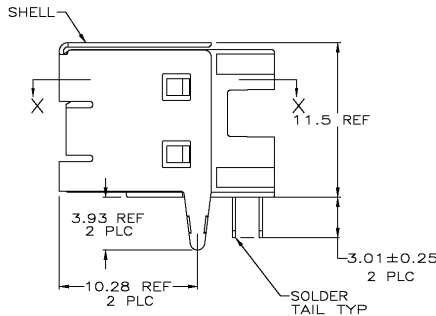
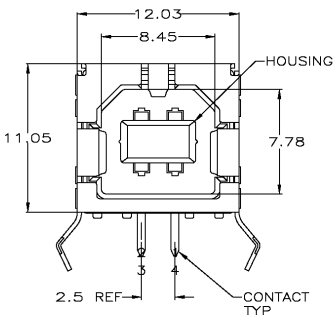
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LOC	PICT	REVISIONS	
F	REV	DESCRIPTION	DATE
ES	00	B	REVISED (ECR-05-014095)
			11/01/05



PC BOARD MOUNTING DIMENSIONS



- △ MATERIAL:
SHELL & CONTACTS: COPPER ALLOY.
HOUSING: UL 94V-0 RATED, THERMOPLASTIC, BLACK.
- △ PLATING:
CONTACTS: 0.076µm MINIMUM GOLD OVER 0.76µm MINIMUM PALLADIUM-NICKEL ON MATING AREA.
3.8µm MINIMUM MATTE TIN ON SOLDER TAILS.
BOTH OVER 1.27µm MINIMUM NICKEL.
CONTACT ALTERNATE PLATING: 0.76µm MIN GOLD ON MATING AREA, 3.8µm MIN MATTE TIN ON SOLDER TAILS, BOTH OVER 1.27µm MIN NICKEL.
SHELL: 2.0~5.0µm MINIMUM TIN.
- △ DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.
- △ RECOMMENDED PC BOARD THICKNESS OF 1.57.
- △ PLATING:
CONTACTS: 0.76µm MINIMUM GOLD ON MATING AREA, 3.8µm MINIMUM MATTE TIN ON SOLDER TAILS, BOTH OVER 1.27µm MINIMUM NICKEL.
SHELL: 2.0~5.0µm MINIMUM TIN.
- △ PLATING:
CONTACTS: 0.38µm MINIMUM GOLD ON MATING AREA, 3.8µm MINIMUM MATTE TIN ON SOLDER TAILS, BOTH OVER 1.27µm MINIMUM NICKEL.
SHELL: 2.0~5.0µm MINIMUM TIN.
- 7 RECOMMEND:
MATING FORCE: 35N MAX.
UNMATING FORCE: 13N MIN.
RECOMMENDED MATING PLUG SHOULD MEET USB2.0 STANDARD.

△	NO	BLACK	292304-5
△	NO	BLACK	292304-4
△	YES	BLACK	292304-3
△	YES	NATURAL	292304-2
△	NO	BLACK	292304-1
PLATING	HIGH TEMPERATURE COMPATIBLE	HOUSING COLOR	PART NUMBER

DIMENSIONS: mm TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 R.C. ± 0.05 1 R.C. ± 0.1 2 R.C. ± 0.15 3 R.C. ± 0.2 4 R.C. ± 0.25 H. R.C. ± 0.3 ANGLES PER 30				DWG: J. JIANG DATE: 23FEB04 CHK: S. YAO DATE: 23FEB04 DTD: T. SASAKI PRODUCT CODE:	 Tyco electronics corporation Shanghai, P.R.China, 200233
MATERIAL: △		SIZE: A2	ORDER CODE: 00779		
CUSTOMER DRAWING		DRAWING NO: C-292304			
		SCALE: 5:1			

292304

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